

Surface Mount Glass Passivated Bridge Rectifier

Voltage

1000 V

Current

2A

Features

- Glass passivated chip junction
- Ideally suited for automatic assembly
- High Surge Current Capability
- Designed for Surface Mount Application
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

- Case : ABS Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.0031 ounces, 0.088 grams

Application

- Quick Charger (<20W)
- General power adapter (<30W)
- In-door Led lighting, Bulb/ PAR lighting
- Netcom power (<35W)
- Smart speaker adapter (<20W)

ABS



Maximum Ratings and Thermal Characteristics ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNITS
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Current	$I_{F(AV)}$	2	A
Peak Forward Surge Current : 8.3 ms Single Half Sine-Wave Superimposed On Rated Load	@ $T_A = 25\text{ }^\circ\text{C}$	70	A
	@ $T_A = 125\text{ }^\circ\text{C}$	56	
Peak Forward Surge Current : 1.0 ms Single Half Sine-Wave Superimposed On Rated Load	@ $T_A = 25\text{ }^\circ\text{C}$	140	A
	@ $T_A = 125\text{ }^\circ\text{C}$	112	
$I^2 t$ rating for fusing ($t = 8.3\text{ms}$)	$I^2 t$	20.3	A^2S
Typical Junction Capacitance Measured at 1 MHZ And Applied $V_R = 4\text{ V}$	C_J	25	pF
Typical Thermal Resistance (Note 1) (Note 2)	$R_{\theta JA}$	60	$^\circ\text{C/W}$
	$R_{\theta JC}$	16	
Operating Junction Temperature Range	T_J	-55~150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55~150	$^\circ\text{C}$

Electrical Characteristics ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Forward Voltage	V_F	$I_F = 2\text{ A}, T_J = 25\text{ }^\circ\text{C}$	-	-	1.1	V
Reverse Current	I_R	$V_R = 1000\text{ V}, T_J = 25\text{ }^\circ\text{C}$	-	-	5	uA
		$V_R = 1000\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	100	

NOTES :

1. Mounted on a FR4 PCB standard pad
2. Mounted on glass epoxy PC board with 4x1.5x1.5(3.81x3.81 cm) copper pad area

TYPICAL CHARACTERISTIC CURVES

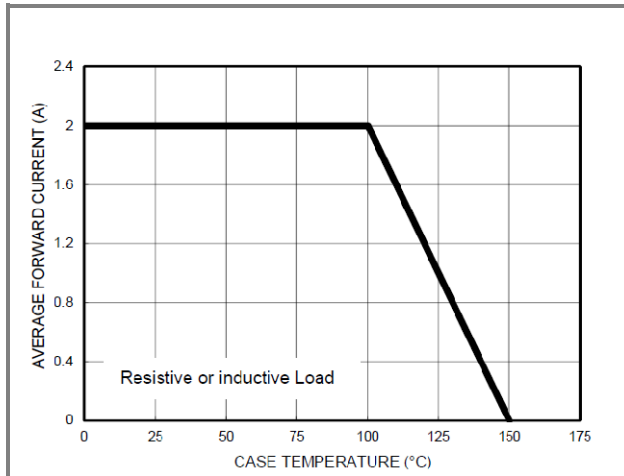


Fig.1 Forward Current Derating Curve

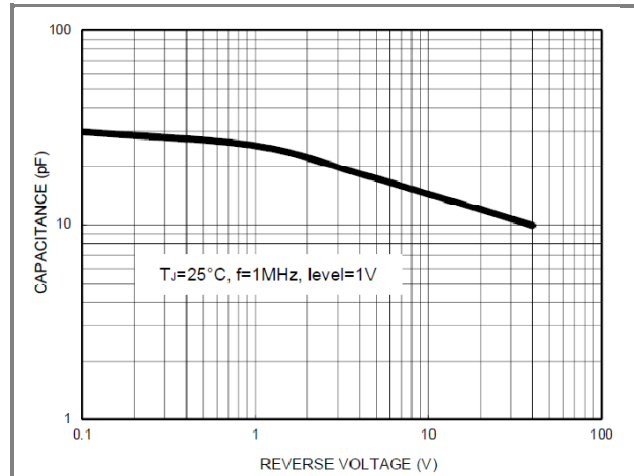


Fig.2 Typical Junction Capacitance

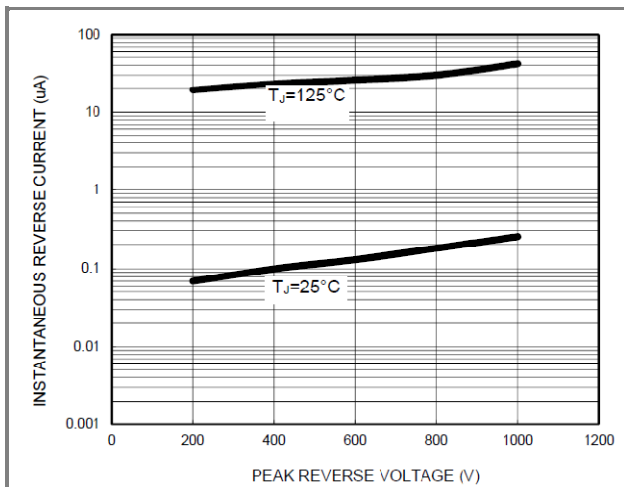


Fig.3 Typical Reverse Characteristics

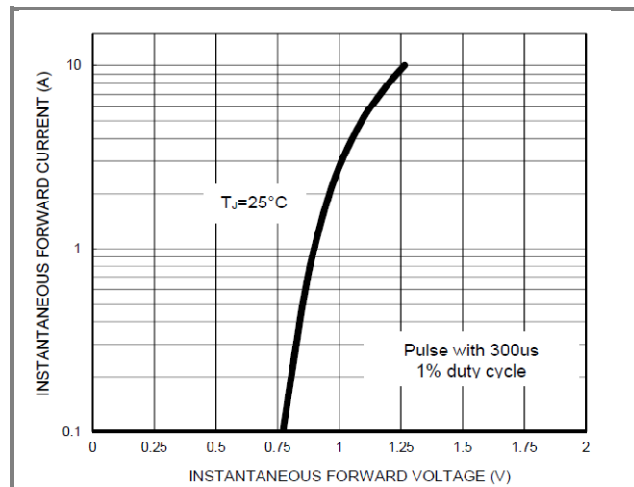


Fig.4 Typical Forward Characteristics

Part No. Packing Code Version

Part No. Packing Code	Package Type	Packing Type	Marking
ABS2MS_R2_00101	ABS	4K pcs / 13" reel	ABS2MS

Packaging Information & Mounting Pad Layout

